

SSM3K56CT

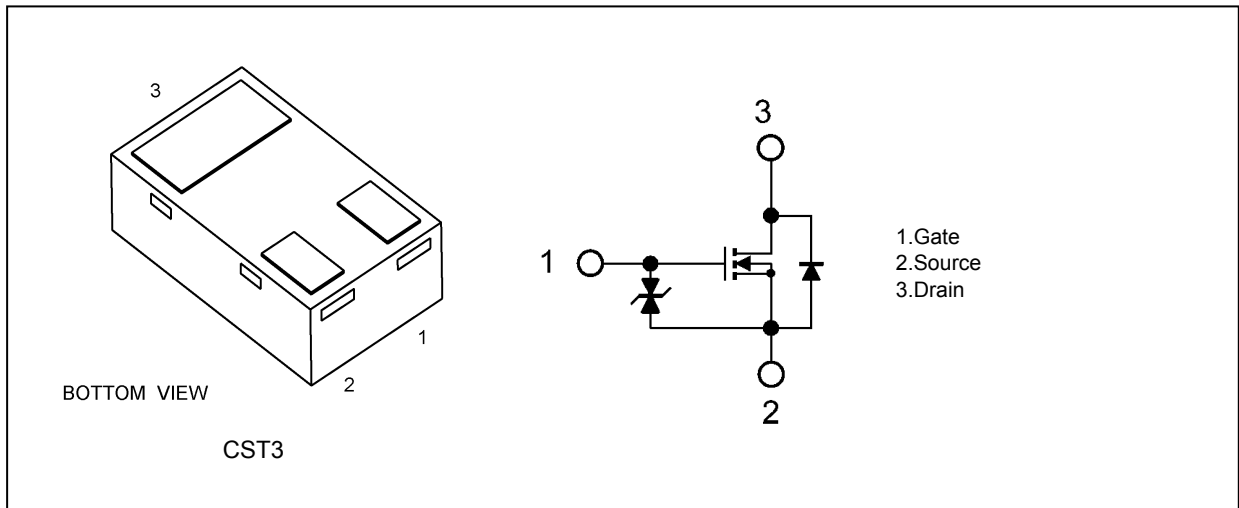
1. Applications

- High-Speed Switching

2. Features

- (1) 1.5-V gate drive voltage.
- (2) Low drain-source on-resistance
 : $R_{DS(ON)} = 235 \text{ m}\Omega$ (max) (@ $V_{GS} = 4.5 \text{ V}$)
 $R_{DS(ON)} = 300 \text{ m}\Omega$ (max) (@ $V_{GS} = 2.5 \text{ V}$)
 $R_{DS(ON)} = 480 \text{ m}\Omega$ (max) (@ $V_{GS} = 1.8 \text{ V}$)
 $R_{DS(ON)} = 840 \text{ m}\Omega$ (max) (@ $V_{GS} = 1.5 \text{ V}$)

3. Packaging and Pin Configuration



4. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25^\circ\text{C}$)

| Characteristics | Symbol | Rating | Unit |
|------------------------|----------------------------|------------|------------------|
| Drain-source voltage | V_{DSS} | 20 | V |
| Gate-source voltage | V_{GSS} | ± 8 | |
| Drain current (DC) | (Note 1) I_D | 800 | mA |
| Drain current (pulsed) | (Note 1),(Note 2) I_{DP} | 1600 | |
| Power dissipation | (Note 3) P_D | 500 | mW |
| Channel temperature | T_{ch} | 150 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to 150 | |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Ensure that the channel temperature does not exceed 150°C .

Note 2: Pulse width (PW) $\leq 10 \text{ ms}$, duty $\leq 1\%$

Note 3: Mounted on an FR4 board.(25.4 mm \times 25.4 mm \times 1.6 mm, Cu Pad: 645 mm²)

Start of commercial production

2013-04

Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.

Note: The channel-to-ambient thermal resistance, $R_{th(ch-a)}$, and the power dissipation, P_D , vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.

5. Electrical Characteristics

5.1. Static Characteristics (Unless otherwise specified, $T_a = 25^\circ\text{C}$)

| Characteristics | Symbol | Test Condition | Min | Typ. | Max | Unit |
|---|---------------|--|-----|------|---------|------------------|
| Gate leakage current | I_{GSS} | $V_{GS} = \pm 6\text{ V}, V_{DS} = 0\text{ V}$ | — | — | ± 1 | μA |
| Drain cut-off current | I_{DSS} | $V_{DS} = 16\text{ V}, V_{GS} = 0\text{ V}$ | — | — | 1 | |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $I_D = 1\text{ mA}, V_{GS} = 0\text{ V}$ | 20 | — | — | V |
| Drain-source breakdown voltage (Note 1) | $V_{(BR)DSX}$ | $I_D = 1\text{ mA}, V_{GS} = -5\text{ V}$ | 15 | — | — | |
| Gate threshold voltage (Note 2) | V_{th} | $V_{DS} = 3\text{ V}, I_D = 1\text{ mA}$ | 0.4 | — | 1.0 | |
| Drain-source on-resistance (Note 3) | $R_{DS(ON)}$ | $I_D = 800\text{ mA}, V_{GS} = 4.5\text{ V}$ | — | 186 | 235 | $\text{m}\Omega$ |
| | | $I_D = 600\text{ mA}, V_{GS} = 2.5\text{ V}$ | — | 230 | 300 | |
| | | $I_D = 200\text{ mA}, V_{GS} = 1.8\text{ V}$ | — | 290 | 480 | |
| | | $I_D = 50\text{ mA}, V_{GS} = 1.5\text{ V}$ | — | 360 | 840 | |
| Forward transfer admittance (Note 3) | $ Y_{fs} $ | $V_{DS} = 3\text{ V}, I_D = 200\text{ mA}$ | — | 1.4 | — | S |

Note 1: If a reverse bias is applied between gate and source, this device enters $V_{(BR)DSX}$ mode. Note that the drain-source breakdown voltage is lowered in this mode.

Note 2: Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to below (1 mA for this device). Then, for normal switching operation, $V_{GS(ON)}$ must be higher than V_{th} , and $V_{GS(OFF)}$ must be lower than V_{th} . This relationship can be expressed as: $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$.

Take this into consideration when using the device.

Note 3: Pulse measurement.

5.2. Dynamic Characteristics (Unless otherwise specified, $T_a = 25^\circ\text{C}$)

| Characteristics | Symbol | Test Condition | Min | Typ. | Max | Unit |
|--------------------------------|-----------|--|-----|------|-----|-------------|
| Input capacitance | C_{iss} | $V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V},$ $f = 1\text{ MHz}$ | — | 55 | — | pF |
| Reverse transfer capacitance | C_{rss} | | — | 6 | — | |
| Output capacitance | C_{oss} | | — | 16 | — | |
| Switching time (turn-on time) | t_{on} | $V_{DD} = 10\text{ V}, I_D = 200\text{ mA}$ $V_{GS} = 0\text{ to }2.5\text{ V}, R_G = 50\ \Omega,$ Duty $\leq 1\%$, Input: $t_r, t_f < 5\text{ ns}$ Common source, See Chapter 5.3 | — | 5.5 | — | ns |
| Switching time (turn-off time) | t_{off} | | — | 8.5 | — | |

5.3. Switching Time Test Circuit

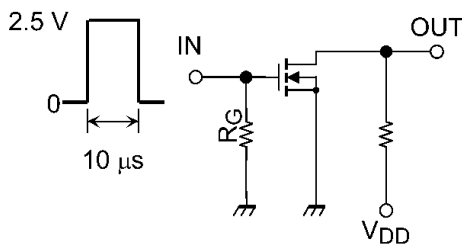


Fig. 5.3.1 Test Circuit of Switching Time

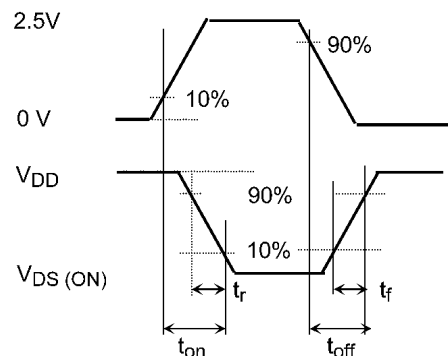


Fig. 5.3.2 Input Waveform/Output Waveform

5.4. Gate Charge Characteristics (Unless otherwise specified, $T_a = 25^\circ\text{C}$)

| Characteristics | Symbol | Test Condition | Min | Typ. | Max | Unit |
|---|-----------|---|-----|------|-----|------|
| Total gate charge (gate-source plus gate-drain) | Q_g | $V_{DD} = 10\text{ V}, V_{GS} = 4.5\text{ V},$ $I_D = 800\text{ mA}$ | — | 1.0 | — | nC |
| Gate-source charge 1 | Q_{gs1} | | — | 0.12 | — | |
| Gate-drain charge | Q_{gd} | | — | 0.4 | — | |

5.5. Source-Drain Characteristics (Unless otherwise specified, $T_a = 25^\circ\text{C}$)

| Characteristics | Symbol | Test Condition | Min | Typ. | Max | Unit |
|--------------------------------|-----------|---|-----|-------|------|------|
| Diode forward voltage (Note 1) | V_{DSF} | $I_D = -800 \text{ mA}, V_{GS} = 0 \text{ V}$ | — | -0.82 | -1.2 | V |

Note 1: Pulse measurement.

6. Marking

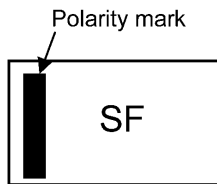
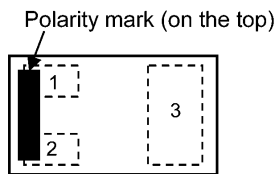


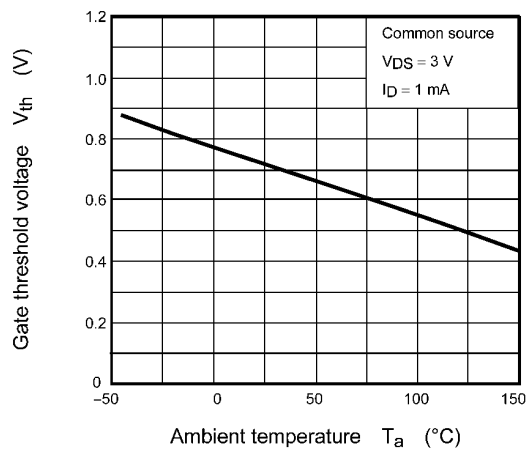
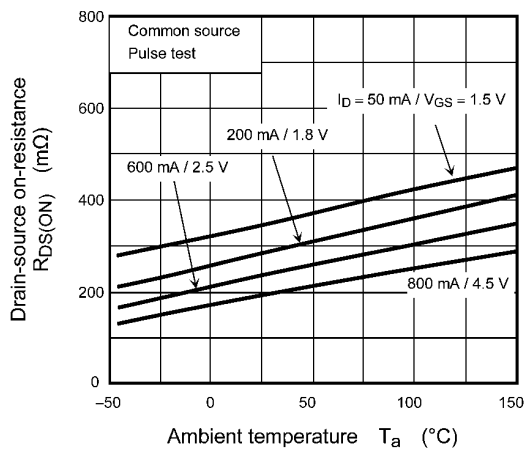
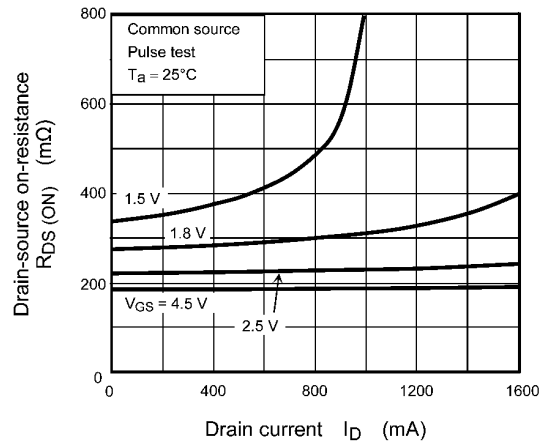
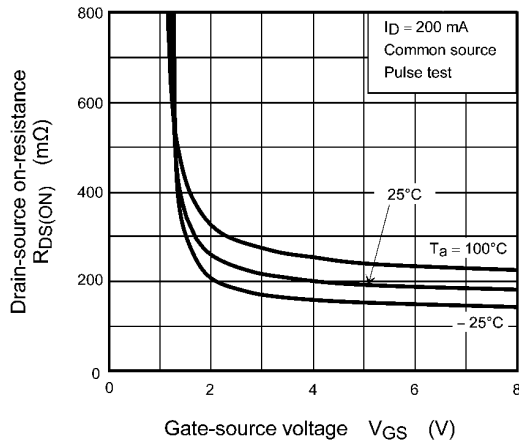
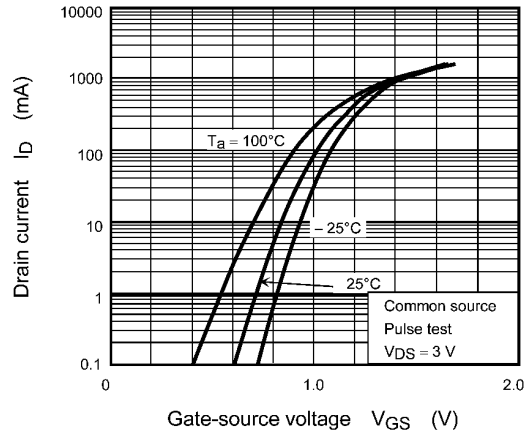
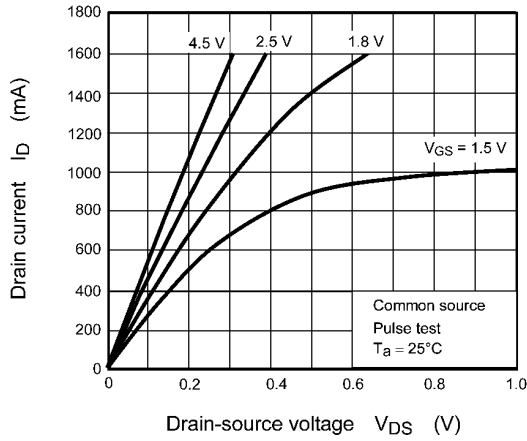
Fig. 6.1 Marking



- 1. Gate
- 2. Source
- 3. Drain
- *Electrodes: On the bottom

Fig. 6.2 Pin Condition(top view)

7. Characteristics Curves (Note)



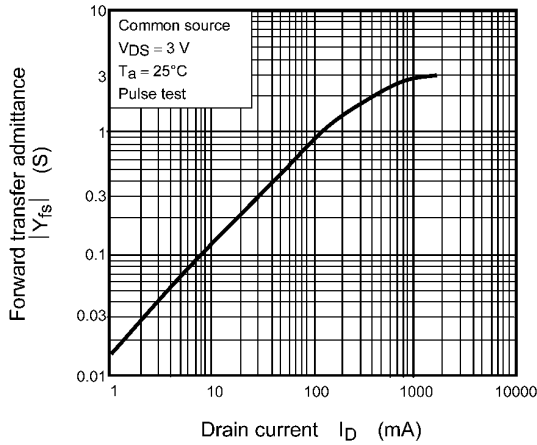


Fig. 7.7 $|Y_{fs}| - I_D$

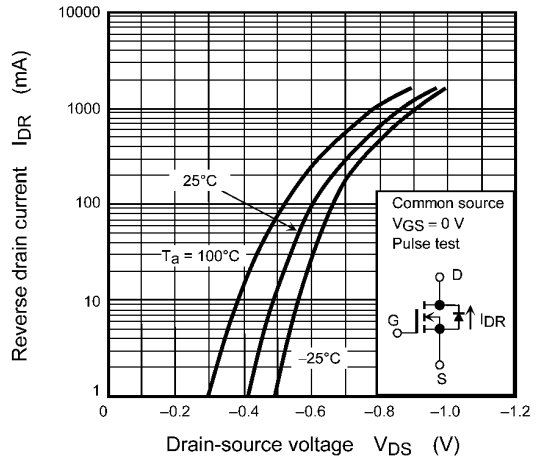


Fig. 7.8 $I_{DR} - V_{DS}$

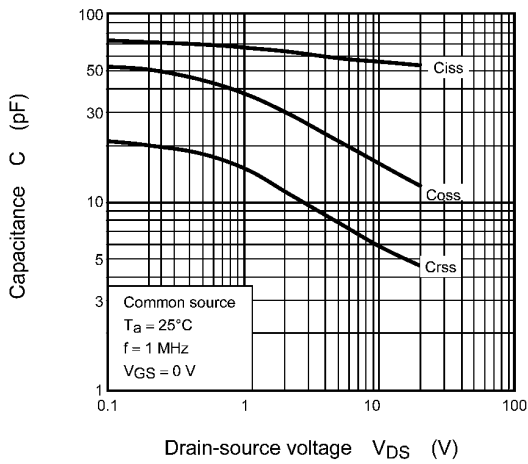


Fig. 7.9 $C - V_{DS}$

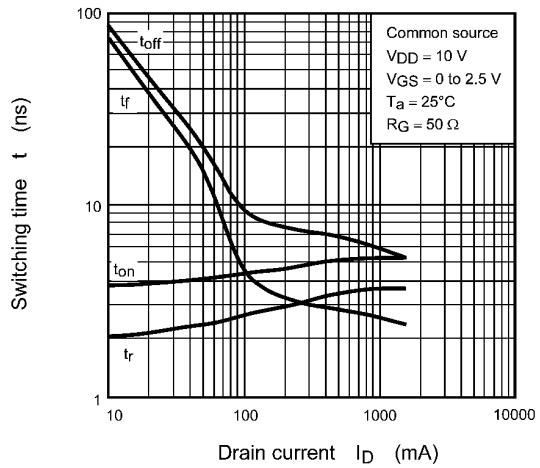


Fig. 7.10 $t - I_D$

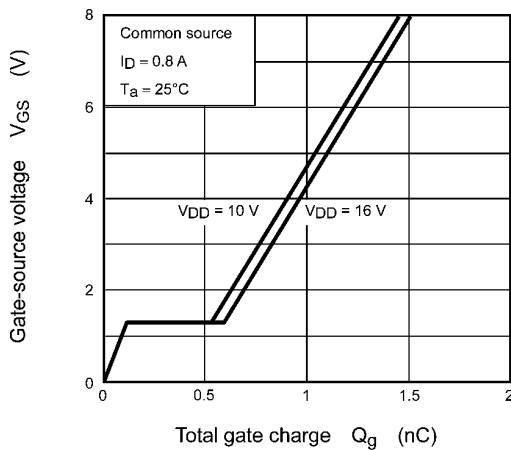


Fig. 7.11 Dynamic Input Characteristics

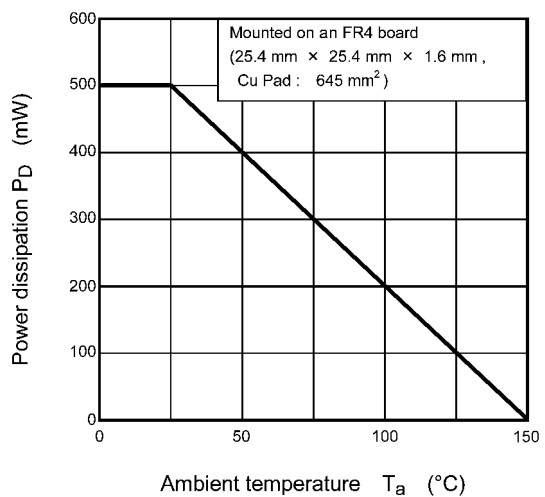
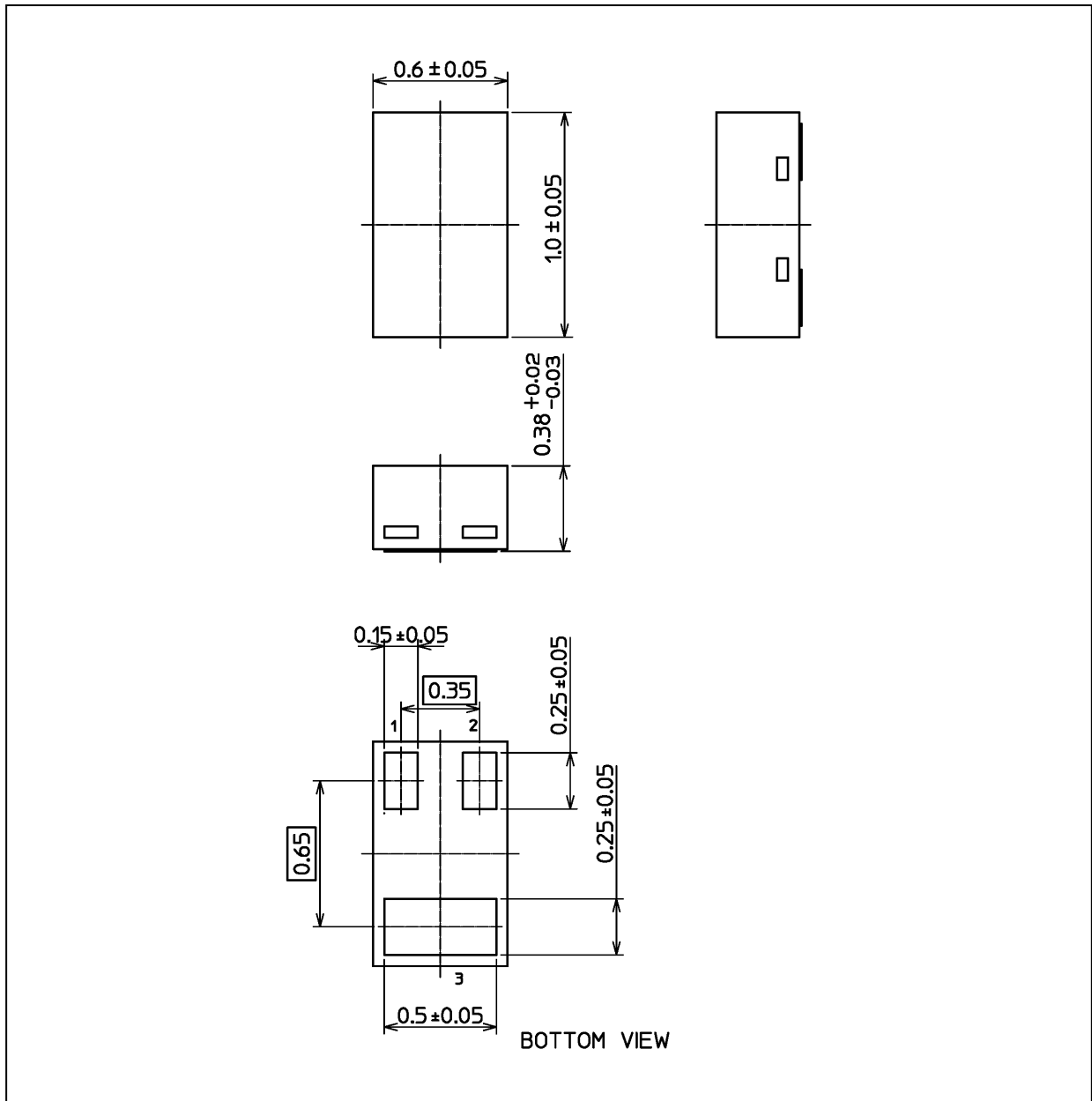


Fig. 7.12 $P_D - T_a$

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 0.75 mg (typ.)

| |
|-----------------|
| Package Name(s) |
| Nickname: CST3 |

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